

# PATENT ASSIGNMENT

Electronic Version v1.1

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| SUBMISSION TYPE:                                                                     | NEW ASSIGNMENT                    |
| NATURE OF CONVEYANCE:                                                                | ASSIGNMENT                        |
| CONVEYING PARTY DATA                                                                 |                                   |
| Name                                                                                 | Execution Date                    |
| Taisuke HIROOKA                                                                      | 08/28/2003                        |
| RECEIVING PARTY DATA                                                                 |                                   |
| Name:                                                                                | SUMITOMO SPECIAL METALS CO., LTD. |
| Street Address:                                                                      | 4-7-19, Kitahama, Chuo-ku         |
| City:                                                                                | Osaka-shi, Osaka                  |
| State/Country:                                                                       | JAPAN                             |
| Postal Code:                                                                         | 541-0041                          |
| PROPERTY NUMBERS Total: 1                                                            |                                   |
| Property Type                                                                        | Number                            |
| Application Number:                                                                  | 11466475                          |
| CORRESPONDENCE DATA                                                                  |                                   |
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| ATTORNEY DOCKET NUMBER:                                                              | 60303.62/OK                       |
| NAME OF SUBMITTER:                                                                   | /Sonia McVean/                    |
| Total Attachments: 1<br>source=60303-62-PTO-20080229-signed-assignment#page1.tif     |                                   |

OP \$40.00 11466475

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PATENT  
REEL: 020581 FRAME: 0015

**ASSIGNMENT (WORLDWIDE)**

WHEREAS, I, Taisuke HIROOKA (hereinafter referred to as ASSIGNOR), has invented and own a certain invention entitled **THIN-FILM MAGNETIC HEAD WAFER AND METHOD FOR MANUFACTURING THE WAFER** for which application for Letters Patent of the United States has been

\_\_\_\_\_ executed on even date herewith;  
X filed on June 13, 2003 as Serial No. 10/460,371.

WHEREAS, SUMITOMO SPECIAL METALS CO., LTD. 4-7-19, Kitahama, Chuo-ku, Osaka-shi, Osaka 541-0041, JAPAN (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention and the United States Letters Patent to be obtained therefor;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest to the said invention and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms for which the same may be granted; and all Letters Patent and applications therefor through the world, including all the rights accruing by virtue of the International Convention for the Protection of Industrial Property.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce said application, said invention and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.

Dated: August 28, 2003

Taisuke Hirooka  
Taisuke HIROOKA